

In the Claims:

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1-8. (Withdrawn)

9-28. (Cancelled)

29. (New) A semiconductor package, comprising:

a leadframe having:

a die pad defining opposed upper and lower surfaces; and

a plurality of bonding pads disposed at least partially about the die pad in spaced relation thereto, each of the bonding pads defining opposed upper and lower surfaces;

a die attached to the upper surface of the die pad and electrically connected to at least one of the bonding pads; and

a molding compound at least partially encapsulating the die and the leadframe such that portions of the bonding pads which define the lower surfaces thereof protrude from a lower surface of the molding compound.

30. (New) The semiconductor package of Claim 29 wherein the die is attached to the upper surface of the die pad through the use of an adhesive material.

31. (New) The semiconductor package of Claim 30 wherein the adhesive material comprises an epoxy.

32. (New) The semiconductor package of Claim 29 wherein the die is electrically connected to the bonding pads via bonding wires which are encapsulated by the molding compound.

33. (New) The semiconductor package of Claim 29 wherein the molding compound comprises a resin.

34. (New) The semiconductor package of Claim 29 wherein a portion of the die pad defining the lower surface thereof protrudes from the lower surface of the molding compound.

35. (New) The semiconductor package of Claim 29 wherein:

the lower surface of the molding compound is generally planar;

the lower surface of each of the bonding pads is generally planar; and

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the lower surfaces of the bonding pads and the lower surface of the molding compound extend along respective ones of a spaced, generally parallel pair of planes.

36. (New) The semiconductor package of Claim 35 wherein a portion of the die pad defining the lower surface thereof protrudes from the lower surface of the molding compound.

37. (New) The semiconductor package of Claim 36 wherein the lower surface of the die pad is generally planar and extends in generally co-planar relation to the lower surfaces of the bonding pads.

38. (New) The semiconductor package of Claim 29 wherein:

the upper surface of the die pad is generally planar; and

the upper surfaces of the bonding pads are generally planar and extend in generally co-planar relation to the upper surface of the die pad.

39. (New) A semiconductor package, comprising:

a leadframe having a plurality of bonding pads defining opposed upper and lower surfaces;

a die electrically connected to at least one of the bonding pads; and

a molding compound at least partially encapsulating the die and the leadframe such that portions of the bonding pads which define the lower surfaces thereof protrude from a lower surface of the molding compound.

40. (New) The semiconductor package of Claim 39 wherein the leadframe further comprises a die pad defining opposed upper and lower surfaces, the die being attached to the upper surface of the die pad.

41. (New) The semiconductor package of Claim 40 wherein the die is attached to the upper surface of the die pad through the use of an adhesive material.

42. (New) The semiconductor package of Claim 40 wherein:

the lower surface of the molding compound is generally planar;

the lower surface of each of the bonding pads is generally planar;

the lower surface of the die pad is generally planar; and

the lower surfaces of the bonding pads and the die pad and the lower surface of the molding compound extend along respective ones of a spaced, generally parallel pair of planes.

43. (New) The semiconductor package of Claim 39 wherein the die is electrically connected to the bonding pads via bonding wires which are encapsulated by the molding compound.

44. (New) A semiconductor package, comprising:

a leadframe having:

a die pad defining opposed upper and lower surfaces; and

at least one bonding pad disposed in spaced relation to the die pad and defining opposed upper and lower surfaces;

a die attached to the upper surface of the die pad and electrically connected to the bonding pad; and

a molding compound at least partially encapsulating the die and the leadframe such that a portion of the bonding pad which defines the lower surface thereof protrudes from a lower surface of the molding compound.

45. (New) The semiconductor package of Claim 44 wherein the die is electrically connected to the bonding pad via a bonding wire which is encapsulated by the molding compound.

46. (New) The semiconductor package of Claim 44 wherein:

the lower surface of the molding compound is generally planar;

the lower surface of the bonding pad is generally planar; and

the lower surface of the bonding pad and the lower surface of the molding compound extend along respective ones of a spaced, generally parallel pair of planes.

47. (New) The semiconductor package of Claim 46 wherein a portion of the die pad defining the lower surface thereof protrudes from the lower surface of the molding compound.

48. (New) The semiconductor package of Claim 47 wherein the lower surface of the die pad is generally planar and extends in generally co-planar relation to the lower surface of the bonding pad.